AMENDMENTS TO THE CLAIMS

Cancel claims 11-14 without prejudice.

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A method comprising:

providing a circuit board having a plurality of holes formed therethrough; and

mounting a spring to apply a load to an underside of the circuit board, the mounted spring having a plurality of holes each aligned with a respective one of the holes in the circuit board;

wherein the spring includes a plurality of bosses, each having one of the holes of the spring formed therethrough, and the method further comprising:

sandwiching each of the bosses of the spring between a respective chassis standoff and a respective heat sink standoff;

wherein said circuit board holes are ~~shaped and sized so that said circuit board is not sandwiched between said chassis standoffs and said heat sink standoffs~~ wide enough in diameter to accommodate the respective chassis standoff and a respective one of the bosses without touching or binding.

2. (original) The method of claim 1, wherein the spring includes at least one spring finger to apply a load to the underside of the circuit board.

3. (canceled)

4. (previously presented) The method of claim 1, further comprising simultaneously inserting a fastener through one of the holes of the circuit board and through a corresponding hole of the spring.

5. (original) The method of claim 2, wherein the plurality of holes of the spring includes four holes.

6. (original) The method of claim 5, wherein the plurality of holes of the circuit board includes four holes located to define a rectangle.

7. (original) The method of claim 1, wherein the mounting of the spring to the underside of the circuit board includes inserting each of a plurality of board attach fingers of the spring through a respective one of the holes of the circuit board.

8-18. (canceled)

19. (currently amended) A system comprising:

a chassis;

a plurality of chassis standoffs mounted on the chassis;

a heat sink having a plurality of heat sink standoffs mounted on a lower side thereof;

a spring including a plurality of bosses each sandwiched between a respective one of the chassis standoffs and a respective one of the heat sink standoffs; and

a circuit board mounted in the chassis with the spring below the circuit board and the heat sink above the circuit board, the heat sink positioned to conduct heat from an integrated circuit (IC) package mounted on an upper side of the circuit board, the circuit board having a respective hole formed therein at a respective location of each of the heat sink standoffs;

the spring including at least one spring finger to apply a load to an underside of the circuit board at a locus of the IC package;

wherein said circuit board holes are ~~shaped and sized so that said circuit board is not sandwiched between said chassis standoffs and said heat sink standoffs~~ wide enough in diameter

to accommodate the respective chassis standoff and a respective one of the bosses without touching or binding.

20. (original) The system of claim 19, wherein the spring includes two spring fingers in contact with the underside of the circuit board.

21. (original) The system of claim 20, further comprising four fasteners each extending downwardly through a respective one of the heat sink standoffs, through a respective hole in the circuit board, through a respective hole in the spring, and into a respective one of the chassis standoffs.